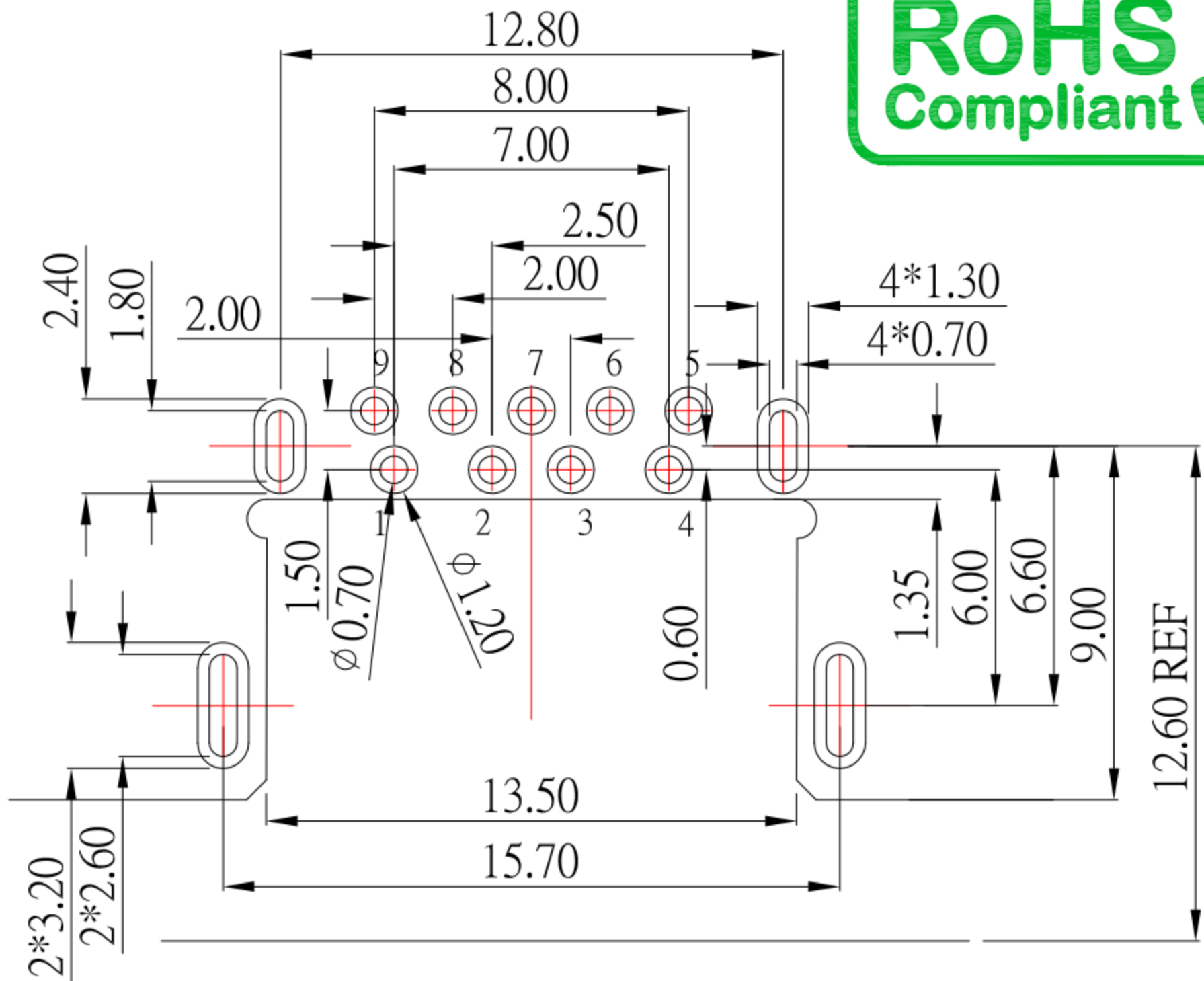
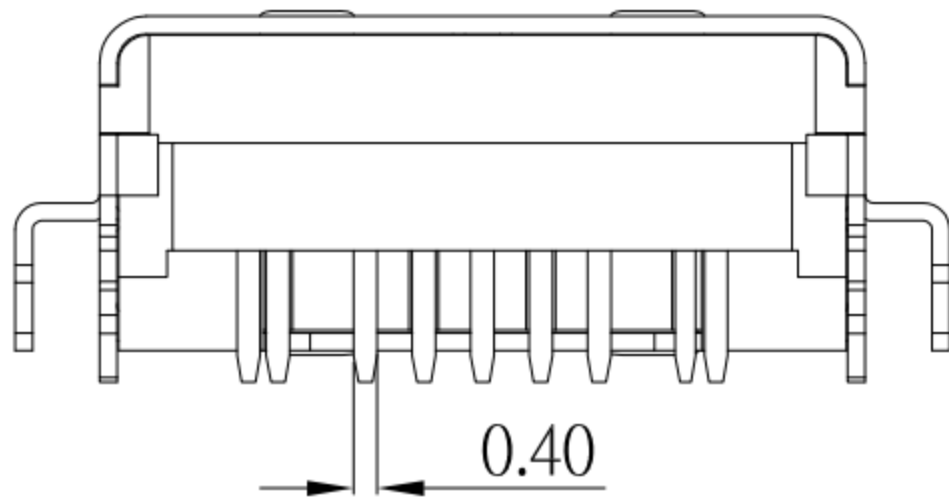
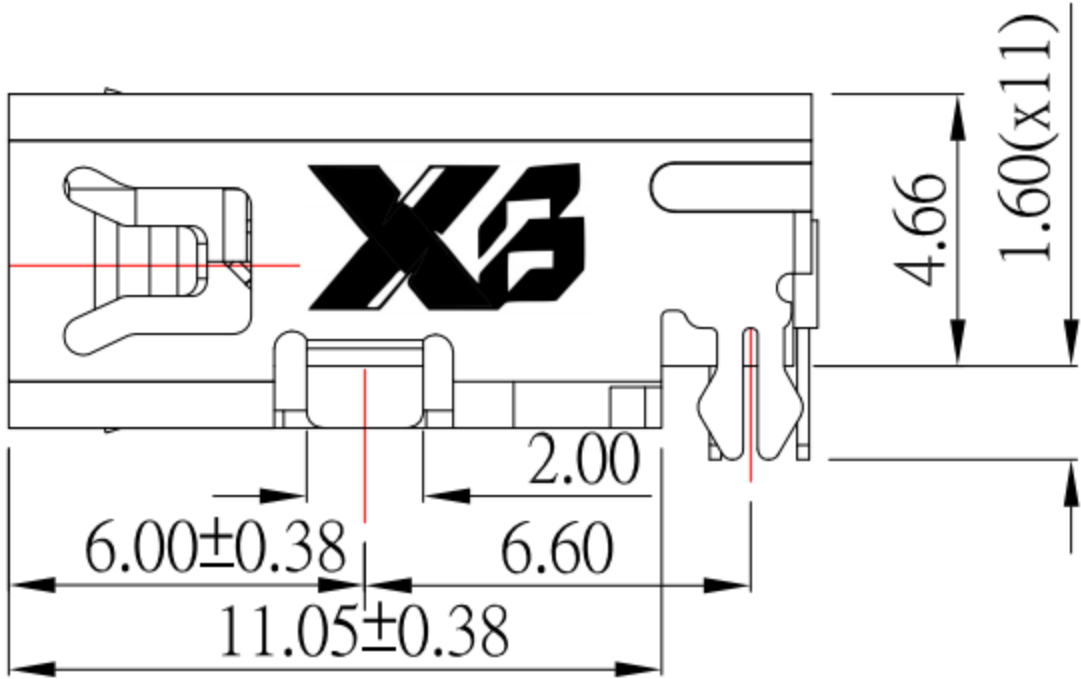
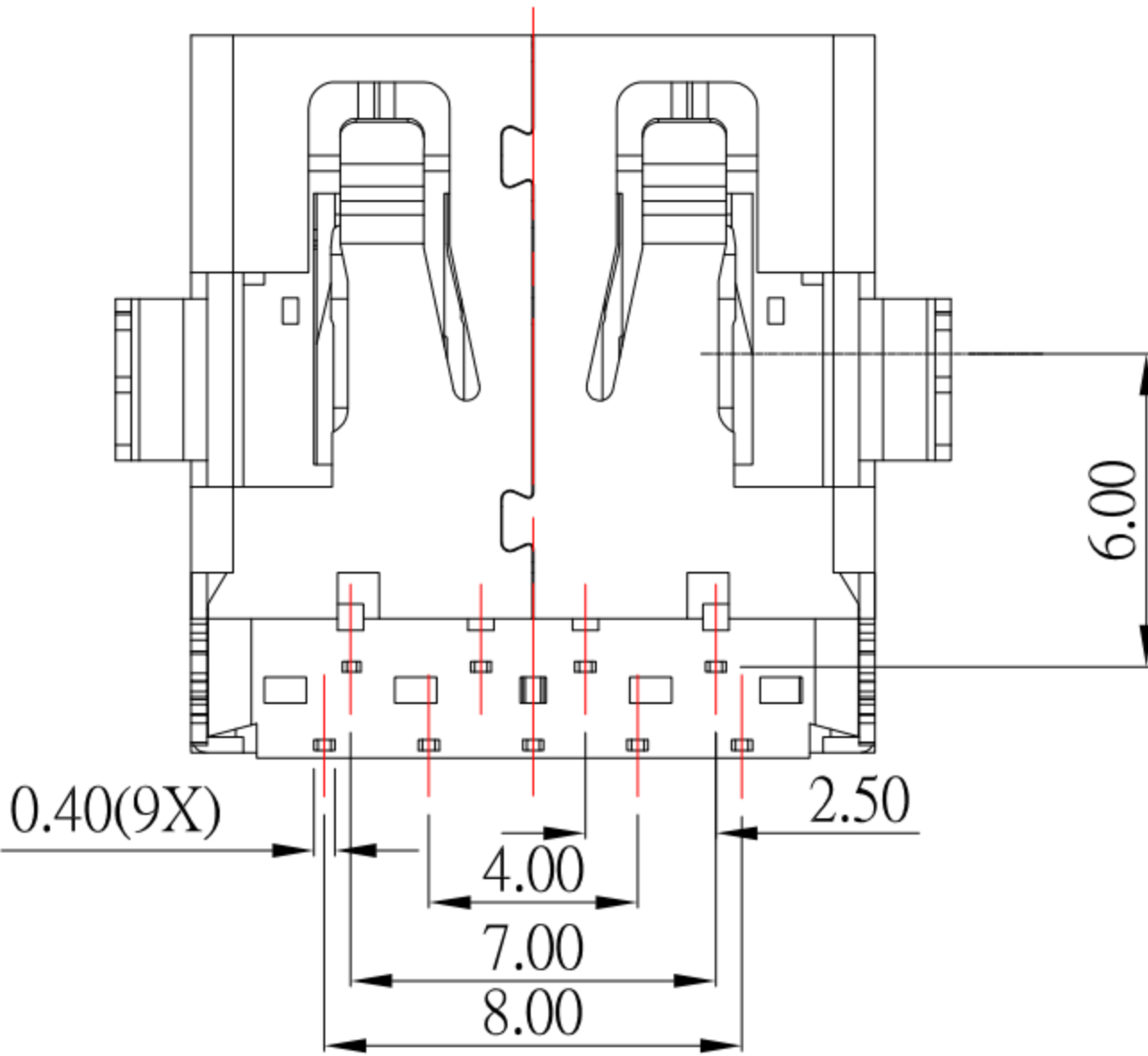
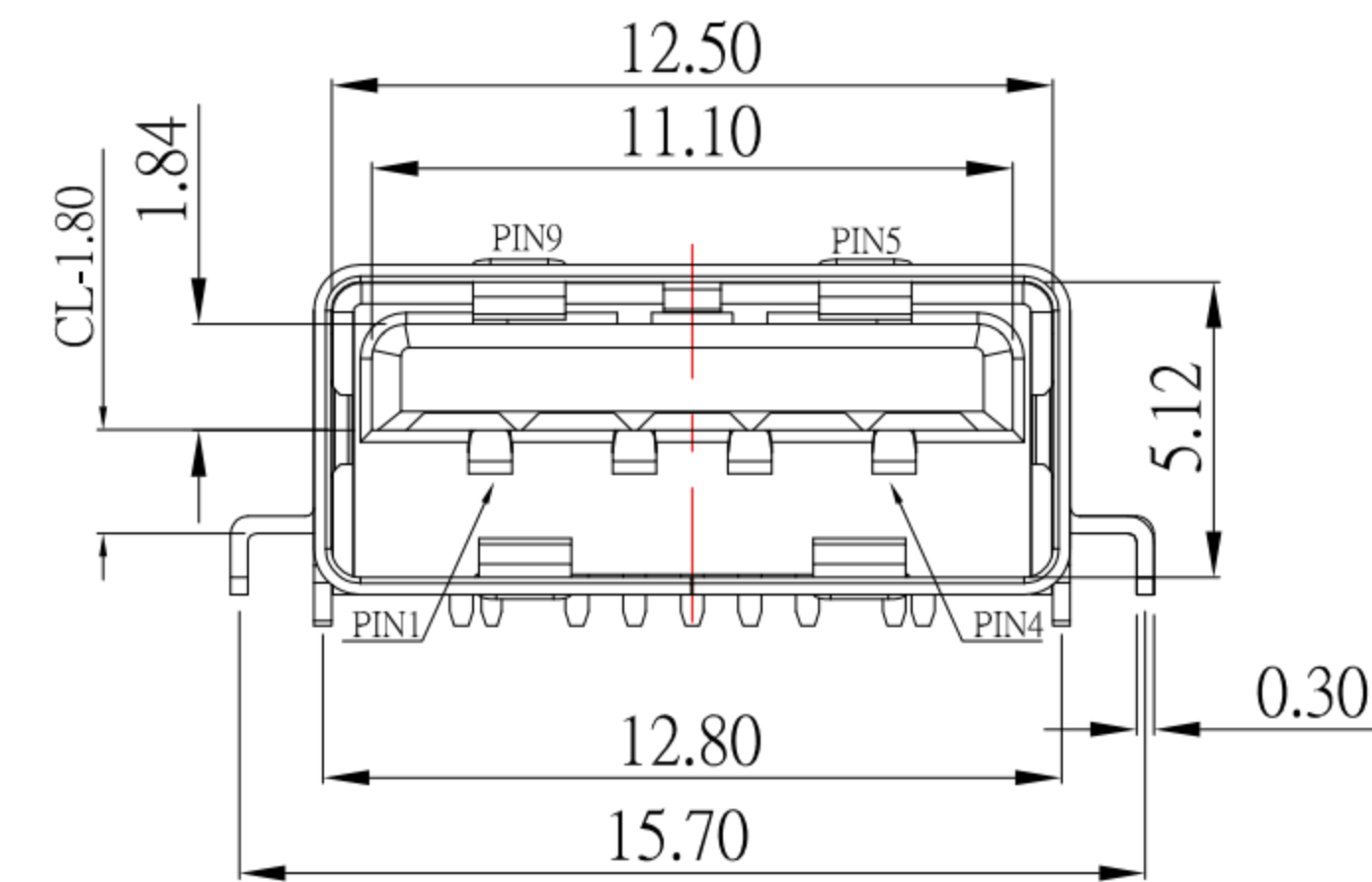
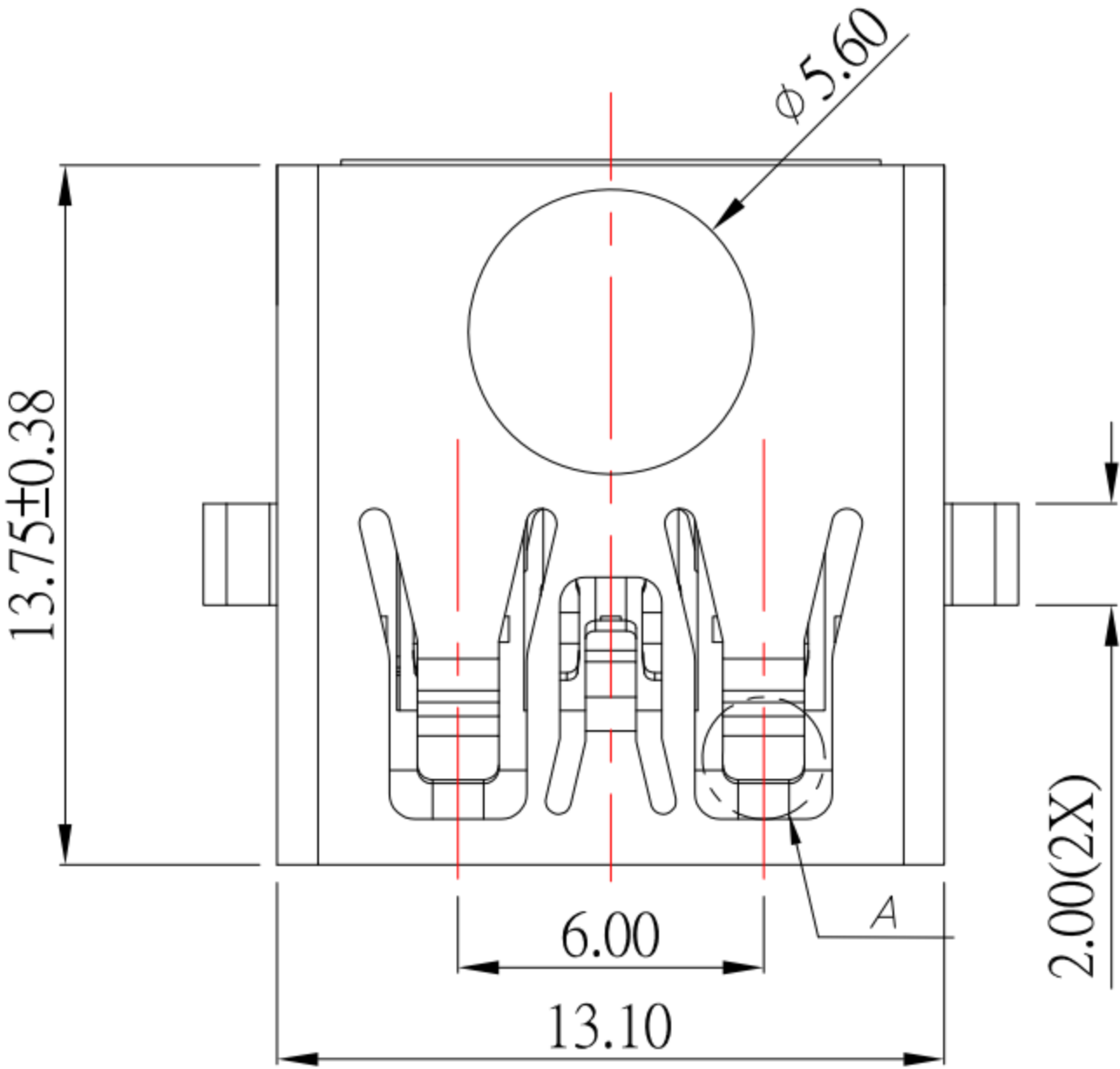




SUA-110E18-30x-S242

鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED PCB LAYOUT

NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS201

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

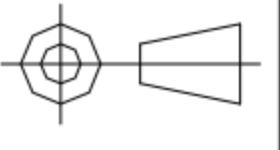
3.SPECIFICATION:

- 3.1 Rate: 30V DC , 1.5 A
- 3.2 Insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55℃ ~ +85℃



东莞市溪榜电子有限公司

DONG GUAN XI BANG ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :		Up to 5 ±0.2 Above 5 ~ 15 ±0.3 Above 15 ~ 30 ±0.4 Above 30 ~ 50 ±0.5 Angle ±0.3°	3RD. ANGEL'S		UNITS	MM
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DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR	
Jack Lu	03/29/22					
CHECKED BY:	DATE	FINISH		MODLE	USB AF 3.0 SMT 沉板 板上H4.46mm L13.75 無捲邊	
Jacky Chen	03/29/22					
APPROVED BY:	DATE	SCALE	1 : 1	DWG NO.	SUA-110E18-30x-S242	SIZE A4
		SHEET NO.	1 of 1	PART NO.	SUA-110E18-30x-S242	VER R2

2	新增尺寸和更新樣式	Jack	032922
1	更新樣式	Jack	032522
ITEM NO.	DESCRIPTION	DRAWN	DATE